

ABSTRACT

An intercoupling component for receiving an array of contacts within a digital or analog transmission system having an electrical ground circuit and chassis ground circuit, the intercoupling component including a segment formed of electrically insulative material and having an upper and lower surface, the segment including a plurality of holes disposed on its upper surface and arranged in a predetermined footprint and one or more shield members formed of electrically conductive material disposed within the segment and configured to connect to the chassis ground circuit of the system. The intercoupling component may include an array of electrically conductive contacts within the plurality of holes disposed on the segment. One or more of these contacts may be configured to electrically connect with the electrical ground circuit of the system. The intercoupling component may also include a cavity located between signal contacts to adjust the differential impedance between signal contacts.

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